

TRANSLATION

from:

PROCESS AND ARRANGEMENT FOR THE ELECTROLYTIC DEPOSITION OF METAL LAYERS

ABSTRACT OF THE DISCLOSURE

For the electrolytic deposition of uniform layers of metal having given physical-mechanical properties, particularly of copper, soluble anodes are not used, since their geometrical shape is changed by the deposition and therefore the distribution of the lines of force in the electrolytic cell are continuously changed.

In order to solve the problems occurring in this connection, a process has been proposed in which compounds of a redox system added to the plating solution are converted during the deposition on the insoluble anodes. The compounds produced in this connection dissolve new metal ions from a reservoir which contains parts of the metal to be deposited, so as again to supplement the metal ions removed from the solution by deposition.

The present invention describes a procedure in which, differing from the prior art, the addition compounds are not destroyed.

Fig. 6

LAWYERS' AND MERCHANTS' TRANSLATION BUREAU INC.

Legal, Financial, Scientific, Technical and Patent Translations
11 BROADWAY, NEW YORK, NY 10004

Tel: (212) 344-2930/2931

Consultant

WM. BERTSCHE, J.D., C.H.E., A.C.S.

Fax: (212) 422-6877

Founded in 1903 by

CARL V. BERTSCHE

This Sheet Has Been Replaced



THIS SHEET HAS BEEN
REPLACED